IN THE CLAIMS

Claim 1 (currently amended): A communication circuit chip for a head comprising:

a first row of connection points positioned along at least one edge of said communication eircuit chip;

a second row of connection points positioned along at least one edge of said communication circuit chip and behind said first row; and

said communication eircuit chip being connected to said head through said first and second rows of connection points.

Claim 2 (currently amended): A communication circuit chip as in Claim 1, wherein said first row of connection points is for a read operation of said head.

Claim 3 (currently amended): A communication eircuit chip as in Claim 1, wherein said second row of connection points is for a write operation of said head.

Claim 4 (currently amended): A communication eircuit chip as in Claim 1, wherein said first row of connection points is for a write operation of said head.

Claim 5 (currently amended): A communication circuit chip as in Claim 1, wherein said second row of connection points is for a read operation of said head.

Claim 6 (currently amended): A communication circuit chip as in Claim 1, wherein said first row and said second row extend along two sides of said communication circuit.